N-Channel Power MOSFET

60 V, 220 A, 3.0 m Ω

Features

- Low R_{DS(on)}
- High Current Capability
- 100% Avalanche Tested
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant
- NVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

MAXIMUM RATINGS (T_J = 25°C Unless otherwise specified)

Para	Symbol	Value	Unit		
Drain-to-Source Volta	V _{DSS}	60	V		
Gate-to-Source Voltage	ge – Conti	nuous	V _{GS}	±20	V
Continuous Drain	Steady	T _C = 25°C	I _D	220	Α
Current, R _{θJC}	State	T _C = 100°C	1	156	
Power Dissipation, $R_{\theta JC}$	Steady State	T _C = 25°C	P _D	283	W
Pulsed Drain Current	t _p	= 10 μs	I _{DM}	660	Α
Current Limited by Package			I _{DMmax}	130	Α
Operating and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			Is	130	Α
Single Pulse Drain-to-Source Avalanche Energy (L = 0.3 mH)			E _{AS}	735	mJ
Lead Temperature for Soldering Purposes (1/8" from Case for 10 Seconds)			TL	260	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case (Drain) Steady State	$R_{\theta JC}$	0.53	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	28	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

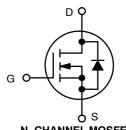
1. Surface mounted on FR4 board using 1 sq in pad size, (Cu Area 1.127 sq in [2 oz] including traces).



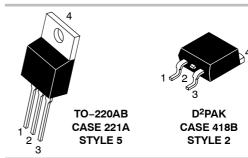
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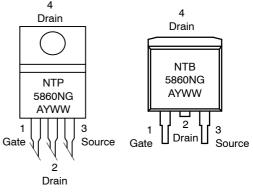
V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX	
60 V	3.0 m Ω @ 10 V	220 A	



N-CHANNEL MOSFET



MARKING DIAGRAMS & PIN ASSIGNMENTS



= Pb-Free Device = Assembly Location*

= Year

WW = Work Week

*Could be one or two digit alpha or numeric code

ORDERING INFORMATION

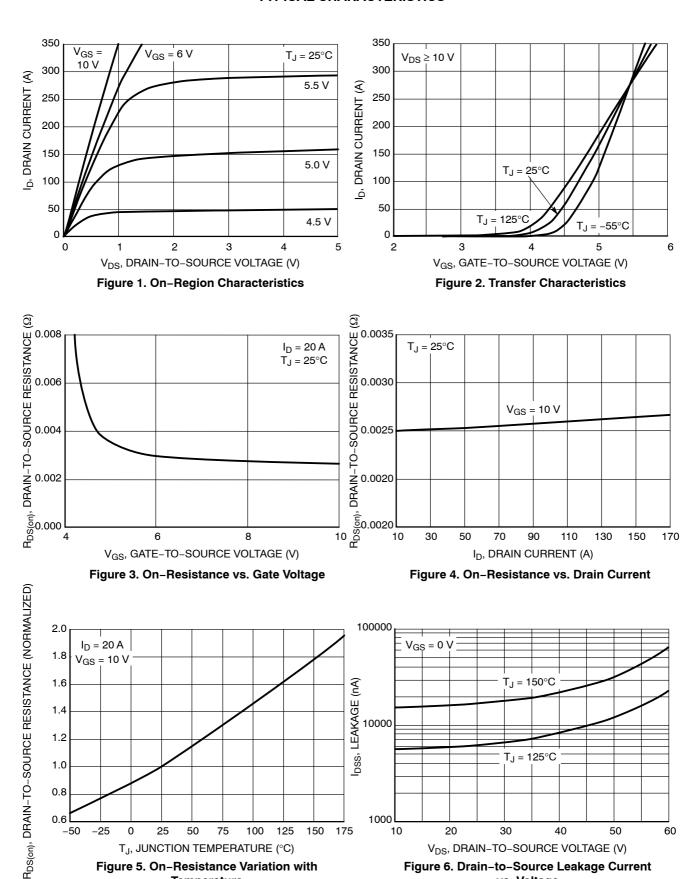
See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25$ °C Unless otherwise specified)

Characteristics	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS				•		•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 2	250 μΑ		5.0		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	T _J = 25°C			1.0	μΑ
		$V_{DS} = 60 \text{ V}$	T _J = 125°C			100	1
Gate-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V	/ _{GS} = ±20 V			±100	nA
ON CHARACTERISTICS (Note 2)				-			
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}$	I _D = 250 μA	2.0		4.0	V
Threshold Temperature Coefficient	V _{GS(th)} /T _J				-10.1		mV/°C
Drain-to-Source On-Resistance	R _{DS(on)}	V _{GS} = 10 \	V, I _D = 75 A		2.5	3.0	mΩ
Forward Transconductance	9FS	V _{DS} = 15 \	/, I _D = 30 A		38		S
CHARGES, CAPACITANCES & GATE RES	SISTANCE						
Input Capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz			10760		pF
Output Capacitance	C _{oss}				1125		
Transfer Capacitance	C _{rss}				700		
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 10 \text{ V}, V_{DS} = 48 \text{ V},$ $I_{D} = 65 \text{ A}$			180		nC
Threshold Gate Charge	Q _{G(TH)}				11		
Gate-to-Source Charge	Q_GS				45		
Gate-to-Drain Charge	Q_{GD}				57		1
SWITCHING CHARACTERISTICS, V _{GS} = 1	10 V (Note 3)					-	
Turn-On Delay Time	t _{d(on)}				27		ns
Rise Time	t _r	V _{GS} = 10 V,	V _{DD} = 48 V,		117		1
Turn-Off Delay Time	t _{d(off)}	$I_D = 65 \text{ A}, R_G = 2.5 \Omega$			66		1
Fall Time	t _f				150		
DRAIN-SOURCE DIODE CHARACTERIST	rics					-	
Forward Diode Voltage		V _{GS} = 0 V	T _J = 25°C		0.76	1.1	V _{dc}
		I _S = 20 A T _J = 125°C		0.63			
Reverse Recovery Time	t _{rr}	V _{GS} = 0 V, I _S = 65 A, dI _S /dt = 100 A/μs			55		ns
Charge Time	ta				29		1
Discharge Time	t _b				26		1
Reverse Recovery Stored Charge	Q _{RR}				76		nC

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



vs. Voltage

Temperature

TYPICAL CHARACTERISTICS

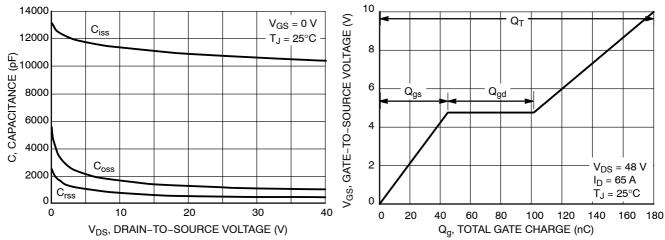


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source vs. Total Charge

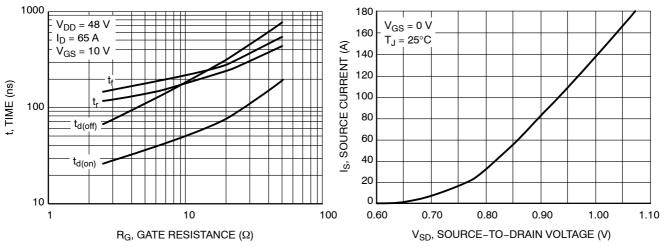


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current

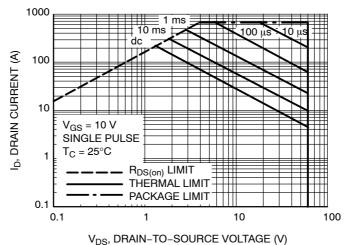


Figure 11. Maximum Rated Forward Biased Safe Operating Area

TYPICAL CHARACTERISTICS

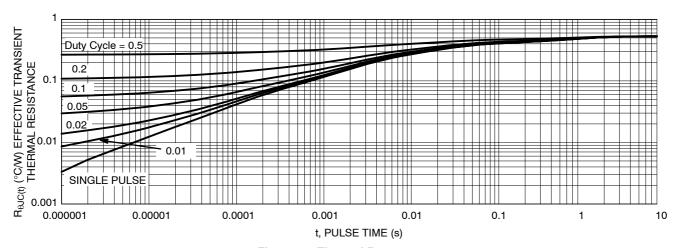


Figure 12. Thermal Response

ORDERING INFORMATION

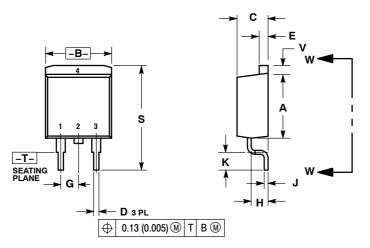
Device	Package	Shipping [†]
NTP5860NG	TO-220AB (Pb-Free)	50 Units / Rail
NTB5860NT4G	D ² PAK (Pb-Free)	800 / Tape & Reel
NVB5860NT4G*	D ² PAK (Pb-Free)	800 / Tape & Reel

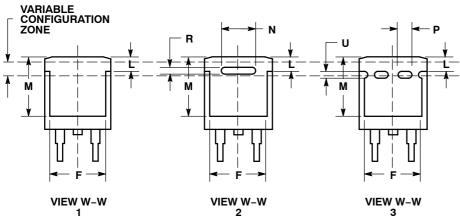
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

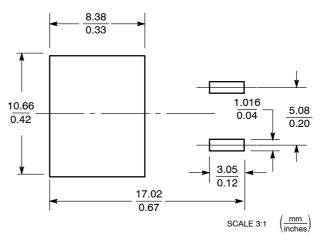
PACKAGE DIMENSIONS

D²PAK CASE 418B-04 **ISSUE J**





SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

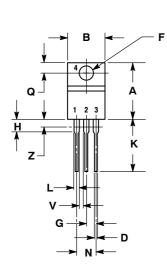
- NOTES:
 1. DIMENSIONING AND TOLERANCING
- PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
- CONTROLLING DIMENSION, INCH.
 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

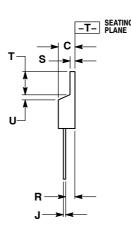
	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.340	0.380	8.64	9.65	
В	0.380	0.405	9.65	10.29	
С	0.160	0.190	4.06	4.83	
D	0.020	0.035	0.51	0.89	
E	0.045	0.055	1.14	1.40	
F	0.310	0.350	7.87	8.89	
G	0.100	BSC	2.54 BSC		
Н	0.080	0.110	2.03	2.79	
J	0.018	0.025	0.46	0.64	
K	0.090	0.110	2.29	2.79	
L	0.052	0.072	1.32	1.83	
М	0.280	0.320	7.11	8.13	
N	0.197 REF		5.00 REF		
P	0.079 REF		2.00 REF		
R	0.039 REF		0.99 REF		
S	0.575	0.625	14.60	15.88	
٧	0.045	0.055	1.14	1.40	

STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AF**





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.161	3.61	4.09	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.014	0.025	0.36	0.64	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
T	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
٧	0.045		1.15		
Z		0.080		2.04	

STYLE 5:

- PIN 1. GATE
 - DRAIN
 - 3 SOURCE DRAIN

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